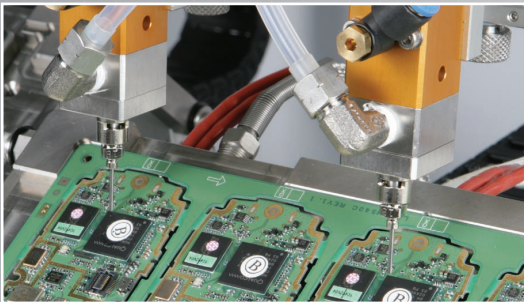


BGA Underfill Dispensing Machine

- BGA(Ball Grid Array)타입의 칩셋이 장착된 PCB기판에 Underfill 액체를 정량 도포하는 로봇장비입니다.
- 히팅(Heating) 및 틸팅(Tilting)방식의 지그로 언더필 액체특성에 대응이 우수한 시스템입니다.
- 멀티 지그방식으로 작업 효율성 및 정밀 액체 토출이 가능한 제품입니다.
- 잔량센싱 액체공급부 및 정밀토출 밸브부로 구성되어있습니다.
- X1, X2축 2개의 Slide 구조로 되어있어 높은 작업 효율성이 특징

- It's a robot equipment dispensing fixed volume of Under-Fill liquid on to PCB that the type of BGA(Ball Grid Array) chipset is equipped to.
- It corresponds to Under-Fill liquids with Jig of Heating and Tilting type.
- It dispenses precisely and the work efficiency is excellent by using Multi axis Jig type.
- It consists of fluid line sensing remains and dispensing Valve.
- It has 2 slides like, X1, X2 axis so that operates efficiently.

*APPLICATION



*SPECIFICATION

ROBOT	Stroke	X axis 1, X axis 2 : 325mm Y axis : 500mm Z axis : 100mm
	Motor Capacity (W)	X axis 1, X axis 2 : 100W AC Servo Motor Y axis : 200W AC Servo Motor Z axis : 100W AC Servo Motor, adhesion Brake
	Speed (mm/sec)	X axis 1, X2 axis, Y axis : 500mm/sec, Z axis : 250mm/sec
	Repeatability (mm)	X, Y : ± 0.02 Z : ± 0.01
	Payload (kgf)	X1, X2, Y axis : 20 kgf Z axis : 7 kgf
	Running part	LM Guide, Ball Screw Type, Clean Type Robot (for dustproof)
Dispensing part		5 axis MULTI TYPE (Including Vacuum Automatic Array SYSTEM) Available for regulating each and fixing Pitch type (Able to correspond to product for each size)
Lay Out Dimensions		890(W)x750(D)x1615(H) - Including Table (Unit : mm)
Fluid line		Epoxy Cartridge Type (mount sensor for liquid remains)
Jig		Heating and Tilting
Dispensing Valve		SV500 series
Needle		SHN-0.3 , SHN-0.4, MNxxG-13